

Docket No.: JCLA19193-CIP5

Form 1595 (Rev. 09/04)

RECORDATION FORM COVER SHEET

U. S. Department of Commerce
Patent and Trademark Office

PATENTS ONLY

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below

1. Name of conveying party(ies) with the
execution date:**GENG-SHIN SHEN**, June 18, 2008**DAVID WEI WANG**, June 18, 2008

2. Name/address of receiving Party(ies)

(1). **ChipMOS TECHNOLOGIES INC.**NO. 1, R&D 1ST RD., SCIENCE-BASED
INDUSTRIAL PARK, HSINCHU, TAIWAN,
R.O.C.(2). **ChipMOS TECHNOLOGIES
(BERMUDA) LTD.**CANNON'S COURT,
22 VICTORIA STREET,
HAMILTON HM12, BERMUDA

3. Nature of conveyance:

- ☒ Assignment ☐ Security Agreement
☐ Merger ☐ Change of Name
☐ Reassignment ☐ Other

Add'l names of receiving parties
Attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

A. Patent Application No. (s)

12/198,536

Additional number attached?

B. Patent No.(s)

☐ Yes ☒ No5. Name and address of party to whom
correspondence concerning document
should be mailed:**J. C. Patents
4 Venture, Suite 250
Irvine, CA 92618
(949) 660-0761**6. Total No. of applications and patents
involved:

ONE (1)

7. Total fee(37CFR§3.41): \$ 40.00

- ☐ Authorized to be charged by credit card
☒ Authorized to be charge to deposit account
☐ Enclosed
☐ None required (government interest not affecting title)

8. Payment Information

- a. Credit Card Last 4 Numbers _____
Expiration Date _____
b. Deposit Account Number 50-0710
Authorized User Name Jiawei Huang

Atty Docket No.: JCLA19193-CIP5

9. Statement and Signature:

To the best of my knowledge and belief, the forging information is true and
Correct and any attached copy is a true copy of the original document.

Jiawei Huang

Name of person Signing
Registration No. 43,330
Signature

8-26-2008

Date

Total number of pages
including cover sheet,
attachments, and
documents: 3

CH \$40.00 500710 12198536

ID-200601010-a5
19193-US-PA-0P5

ASSIGNMENT

WHEREAS, 1. Geng-Shin Shen

2. David Wei Wang

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: CHIP PACKAGE

☐ Filed: Serial No.

☒ Executed concurrently with the execution of this instrument

WHEREAS, 1. ChipMOS Technologies Inc.

of No. 1, R&D 1st Rd., Science-Based Industrial Park Hsinchu, Taiwan, R.O.C.

2. ChipMOS Technologies (Bermuda) Ltd.

of Canon's Court, 22 Victoria Street, Hamilton HM12, Bermuda

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

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ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Geng Shin Shen Date: Jun/18/08

Sole or First Joint Inventor: Geng-Shin Shen

Signature: David Wei Wang Date: 6/18/08

Second Joint Inventor (if any): David Wei Wang